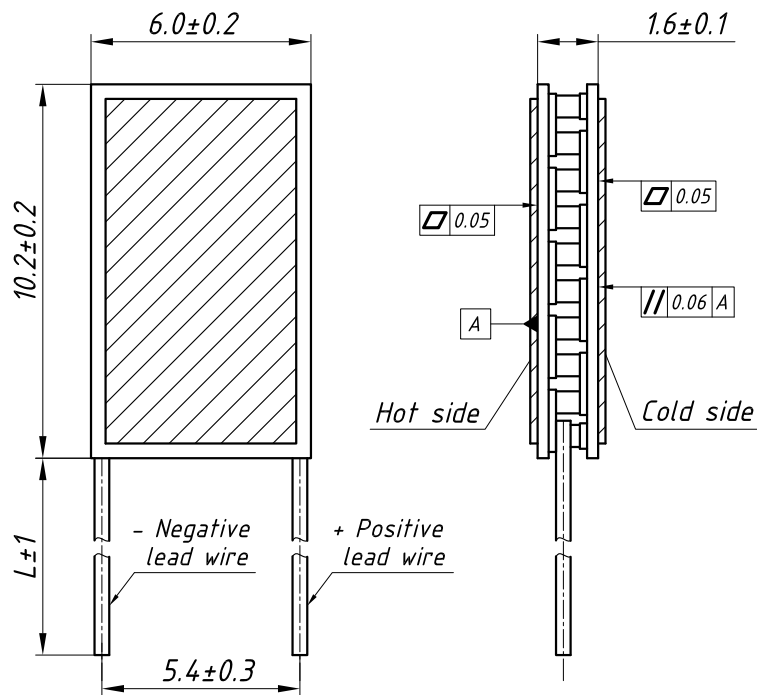


TM-29-0.6-2.0

TECHNICAL DATA

U_{max}	3.3 V	$T_{hot}=25^{\circ}\text{C}$ Vacuum
Q_{max}	4.0 W	
ΔT_{max}	72°	
I_{max}	2.0 A	
ACR at 25°C	1.45 Ohm	
Lead wires type	Cu wire Sn plated $\phi 0.3$ mm	
Solder	Lead Free, m.p.t. $\geq 227^{\circ}\text{C}$	
Metallization	Cu+Ni+Au	
Hot side	Ceramics Al_2O_3 , white 96%	
Cold side		
Maximum processing temperature 180 °C		
Tolerances for thermal and electrical parameters $\pm 10\%$		
This product is compliant to RoHS (2002/95/EC)		

AVAILABLE MODIFICATIONS

Design	Description
TM-29-0.6-2.0 TT	Standard design with metallization on both sides

MODIFICATIONS UPON REQUEST

Design	Description
TM-29-0.6-2.0	Standard design without metallization
TM-29-0.6-2.0 T	Standard design with metallization on the hot side

OPTION UPON REQUEST

Height tolerance	± 0.05
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For another options consult of our technical support engineers

STANDARD ORDERING OPTIONS

Nº	Option	Parameter
1	Lead wires length	$L \geq 30$ mm
2	Lead wires insulation	Maximum processing temperature
	Without insulation	200 °C
3	Sealing	Maximum processing temperature
	No sealing	200 °C
	Epoxy	130 °C
	Silicone	180 °C

Notes

- When applying plus voltage to positive lead wire the module cold side becomes heat absorbing surface.
- Module AC resistance at 25°C does not include resistance of lead wires.

Performance graphs for TM-29-0.6-2.0 modules at Th=25 °C
 Environment: vacuum

